



Flaircomm Microelectronics, Inc.

FLC-WFM011 Datasheet

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1. Introduction

WFM011 module is a highly integrated WIFI communication module (supporting 802.11 b\g\n) specific for IOT market, with its low power consumption, it makes it simple to design into other embedded WiFi solutions with lowest cost and maximum practicability.

WFM011 module is designed with compact size and QFN package. It applies to SMT manufacturing technique, supports standard pick- and- place and fully automatic integration with reflow soldering.

1.1 Block Diagram

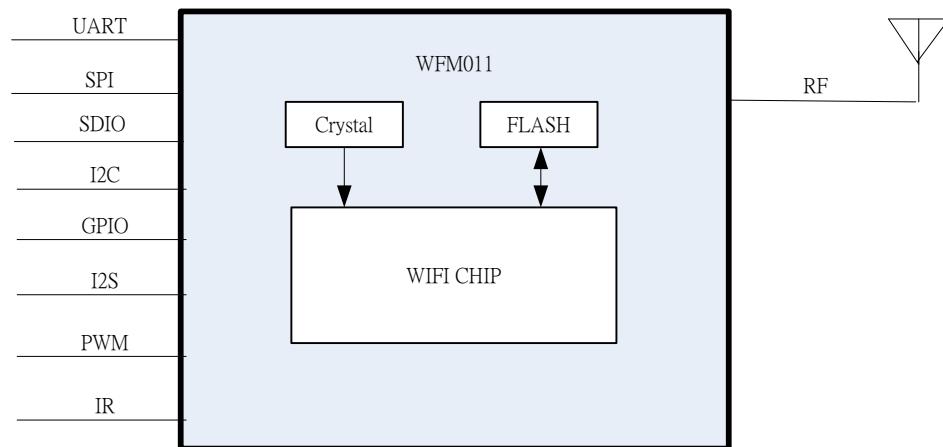


Figure 1: Block Diagram

1.2 Features

- Support 802.11b/g/n;
- Support antenna diversity;
- Built-in 32-bit low-power consumption CPU and can act as a processor currently;
- Built-in 10bit high-precision ADC;
- Built-in TCP/IP protocol stack, TR switch, Balun, LNA, power amplifier and match circuit;
- Built-in PLL, voltage stabilizer and power management module;
- Support WPA/WPA2 safety mode;
- Support STA/AP/STA+AP working mode;

- Support Smart Config function;
- Small size, 62 pins, package size: 15.5*22*3.66mm.

1.3 Applications

- Industrial wireless control
- Smart home;
- Wearable electronics;
- IP camera

2. General Specification

Module Specification		
Frequency band	2.4GHz-2.5GHz	
Wireless standard	802.11b/g/n	
Transmitted power	802.11b	18dBm
	802.11g	16dBm
	802.11n	13dBm
Receiving sensitivity	802.11b	-89dBm (11Mbps)
	802.11g	-74dBm (54Mbps)
	802.11n	-71dBm (MCS7)
Interface	UART SDIO I2C SPI I2S ADC PWM IR	
RF input impedance	50 ohm	
Power supply		
Working Voltage	3.0~3.6V DC	
Working current	80mA	
Operating Environment		
Temperature	-40°C to +85°C	
Humidity	10%~90% Non-condensation	
Dimension and Weight		
Dimension	15.5*22*3.66mm	
Weight	1.05g	

Table 1: General Specification

3. Pin Definition

3.1 Pin Configuration

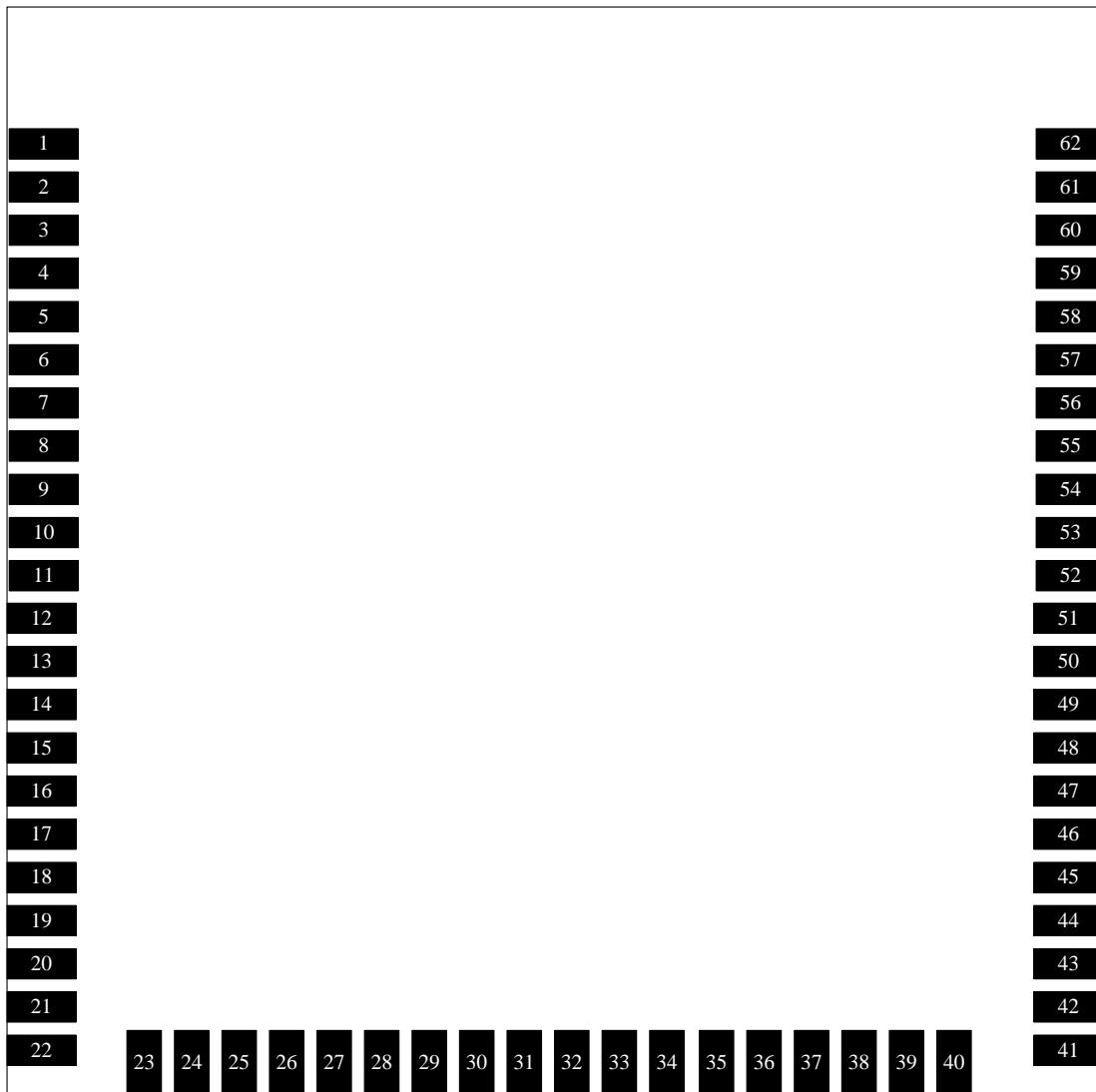


Figure 2: Pin Configuration

3.2 Pin Definition

Pin No	Pin Name	I/O Type	Description
1	GND	I	Ground
2	Reserved	I	Make it open if not use it
3	Reserved	I	Make it open if not use it
4	GND	I	Ground

5	RF_EXT	I/O	Wi-Fi Signal connect external antenna
6	GND	I	Ground
7	Reserved		Make it open if not use it
8	Reserved		Make it open if not use it
9	UART0_TX	O	Serial Port 1 Send Data, FW update, GPIO1,SPI_CS1
10	UART0_RX	I	Serial Port 1 Receive Data, FW update,GPIO3
11	VDD	I	Supply voltage
12	Reserved		Make it open if not use it
13	GND	I	Ground
14	GND	I	Ground
15	GND	I	Ground
16	Reserved		Make it open if not use it
17	GND	I	Ground
18	GND	I	Ground
19	Reserved		Make it open if not use it
20	Reserved		Reserve pin for vacancy
21	GPIO4	I/O	General Purpose IO (vacant if not in use)
22	GND	I	Ground
23	GND	I	Ground
24	GND	I	Ground
25	Reserved		Make it open if not use it
26	RST#	I	RESET
27	TOUT	I	ADC
28	GND	I	Ground
29	GND	I	Ground
30	SDIO_D1	I/O	SDIO DATA1,GPIO8, SPI_MOSI
31	SDIO_CLK	I/O	SDIO CLOCK,GPIO6,SPI_CLK
32	Reserved		Make it open if not use it
33	GND	I	Ground
34	SDIO_D2	I/O	SDIO DATA2,GPIO9,SPIHD,HSPIHD,
35	SDIO_D3	I/O	SDIO DATA3,GPIO10,SPIWP,HSPIWP
36	SDIO_D0	I/O	SDIO DATA0,GPIO7,SPI_MISO

37	SDIO_CMD	I/O	SDIO CONTROL,GPIO11,SPI_CS0
38	Reserved		Make it open if not use it
39	Reserved		Make it open if not use it
40	GND	I	Ground
41	GND	I	Ground
42	Reserved		Make it open if not use it
43	CH_PD	I	CHIP ENABLE
44	GPIO16	I/O	General Purpose IO (vacant if not in use)
45	GPIO5	I/O	General Purpose IO(vacant if not in use)
46	GND	I	Ground
47	Reserved		Make it open if not use it
48	GPIO12	I/O	General Purpose IO (vacant if not in use), HSPI_MISO
49	GPIO13	I/O	General Purpose IO (vacant if not in use), SPI_MOSI,UART0_CTS
50	GPIO15	I/O	General Purpose IO (vacant if not in use) HSPI_CS,UART0_RTS
51	Reserved		Make it open if not use it
52	Reserved		Make it open if not use it
53	Reserved		Make it open if not use it
54	Reserved		Make it open if not use it
55	GPIO2	I/O	General Purpose IO (vacant if not in use) ,UART1_TX
56	GPIO14	I/O	General Purpose IO(vacant if not use it),HSPI_CLK
57	GPIO0	I/O	General Purpose IO (vacant if not in use) ,SPI_CS2
58	Reserved		Make it open if not use it
59	Reserved		Make it open if not use it
60	Reserved		Make it open if not use it
61	VDD	I	Supply voltage
62	Reserved		Make it open if not use it

Table 2: Pin Definition

4. Physical Interfaces

4.1 Power management

The module is provided with two power input pins VDD (pin11, pin61) with input voltage of 3.3V.

4.2 Reset

Module is externally provided with reset signal (RST), active-low level and if external reset signal is provided, the minimum low level period shall be larger than 100us.

4.3 Antenna Interface

Module's antenna interface (RF_OUT) can be directly used to receive and transmit WIFI signal. Module is designed with PCB antenna on own board and may be externally equipped with WIFI antenna, both antenna are different in their models, namely the on-board antenna module WFM011IQ2A and external antenna module WFM011IQ2B.

4.4 Universal programmable IO interface

Module provides 17 GPIO ports in combination with other functions such as I2C, I2S, SPI, UART, PWM, IR infrared control, etc.

4.5 SDIO interface

Module is equipped with a group of SDIO slave ports, it supports 4-bit 25MHz SDIO v1.0 and 4-bit 50MHz SDIO v2.0.

Pin Name	Pin NUM	IO	Function Name
SDIO_CLK	31	GPIO6	SDIO_CLK
SDIO_D0	36	GPIO7	SDIO_DATA0
SDIO_D1	30	GPIO8	SDIO_DATA1
SDIO_D2	34	GPIO9	SDIO_DATA2
SDIO_D3	35	GPIO10	SDIO_DATA3
SDIO_CMD	37	GPIO11	SDIO_CMD

Table 3: SDIO interface

4.6 SPI port

The module defines a universal Slave/Master SPI, a SPI port (SDIO/SPI) and a universal Slave/Master HSPI port defined in Slave SDIO standard. Universal SPI and HSPI is subject to hardware implementation, supports highest clock rate up to 80MHz; SPI Slave interface defined in SDIO Slave standard is subject to hardware implementation, supports linked list DMA with less software overhead; while universal SPI and HSPI has high software overhead since it has no linked list DMA, data transmission therefore is limited by the processing speed.

Pin Name	Pin NUM	IO	Function Name
SDIO_CLK	31	GPIO6	SPI_CLK
SDIO_D0	36	GPIO7	SPI_MISO
SDIO_D1	30	GPIO8	SPI_MOSI
SDIO_D2	34	GPIO9	SPIHD
SDIO_D3	35	GPIO10	SPIWP
SDIO_CMD	37	GPIO11	SPI_CS0
UART_TX	9	GPIO1	SPI_CS1
GPIO0	57	GPIO0	SPI_CS2

Table 4: Definition of universal SPI (Slave/Master) interface

Pin Name	Pin NUM	IO	Function Name
SDIO_CLK	31	GPIO6	SPI_CLK
SDIO_D0	36	GPIO7	SPI_MISO
SDIO_D1	30	GPIO8	SPIWP
SDIO_D2	34	GPIO9	NC
SDIO_D3	35	GPIO10	SPI_CS
SDIO_CMD	37	GPIO11	SPI_MOSI

Table 5: Definition table of SDIO/SPI (Slave) interface

Pin Name	Pin NUM	IO	Function Name
GPIO14	58	GPIO14	HSPI_CLK
GPIO12	48	GPIO12	HSPI_MISO
GPIO13	49	GPIO13	HSPI_MOSI
GPIO15	50	GPIO15	HSPI_CS

Table 6: Definition table of HSPI (Slave/Master) interface

4.7 I²C interface

The module defines a I2C interface (implemented by software), it supports I2C Master and I2C Slave and 100kb/s standard mode.

Pin Name	Pin NUM	IO	Function Name
GPIO14	58	GPIO14	I2C_SCL
GPIO2	55	GPIO2	I2C_SDA

Table 7: I2C interface

4.8 I²S interface

The module defines one I2S input and output interface, mainly used for audio data collection, processing and transmission, and also for serial data input and output.

I2S interface input			
Pin Name	Pin NUM	IO	Function Name
GPIO12	48	GPIO12	I2SI_DATA
GPIO13	49	GPIO13	I2SI_BCK
GPIO14	58	GPIO14	I2SI_WS
I2S interface output			
Pin Name	Pin NUM	IO	Function Name
GPIO15	50	GPIO15	I2SO_BCK
UART_RX	10	GPIO3	I2SO_DATA
GPIO2	55	GPIO2	I2SO_WS

Table 8: I2S interface

4.9 UART interface

Module defines 2 UART interface completed by hardware, with speed up to 115,200*40 (4.5Mbps).

UART0			
Pin Name	Pin NUM	IO	Function Name
UART0_RX	10	GPIO3	UART0_RX
UART0_TX	9	GPIO1	UART0_TX
GPIO15	50	GPIO15	UART0_RTS
GPIO13	49	GPIO13	UART0_CTS

UART1			
Pin Name	Pin NUM	IO	Function Name
GPIO2	55	GPIO2	UART1_TX
SD_D1	30	GPIO8	UART1_RX

Table 9: UART interface

4.10 PWM interface

Module defines 4 PWM output interfaces that can be expanded.

Pin Name	Pin NUM	IO	Function Name
GPIO12	48	GPIO12	PWM0
GPIO15	50	GPIO15	PWM1
GPIO14	56	GPIO14	PWM2
GPIO2	55	GPIO2	PWM3

Table 10: PWM interface

4.11 IR Remote Control interface

The module defines one IR infrared remote-control interface.

Pin Name	Pin NUM	IO	Function Name
GPIO12	48	GPIO12	IR TX
GPIO5	45	GPIO5	IR RX

Table 11: IR Remote Control interface

4.12 ADC interface

The module defines one universal 10bit ADC, with detectable input voltage range of 0-1V.

Pin Name	Pin NUM	Function Name
TOUT	27	ADC port

Table 12: ADC port

5. Electrical Characteristic

5.1 Absolute Maximum Ratings

Parameters		Min	Max	Unit
Storage Temperature		-40	+125	°C
VCC Power supply voltage		-0.3	3.6	V
Digital IO	VIL/ VIH	-0.3/0.75 VIO	0.25VIO /3.6	V
	VOL/ VOH	N/0.8 VIO	0.1 VIO /N	V
	IMAX		12	mA
ESD Stress Voltage Human Body Model			2000	V

Table 13: Absolute rated value

5.2 Recommended Operating Conditions

Operating Condition	Min	Typical	Max	Unit
Operating Temperature Range	-40	25	+85	°C
VCC Power supply voltage	3.0	3.3	3.6	V

Table 14: Recommended Operating Conditions

5.3 WLAN 2.4G RF parameter

5.3.1 Transmitted power

Mode	Rate	CH1	CH6	CH13
11b	2Mbps	18.7dBm	17.5dBm	17.2dBm
	11Mbps	19.1dBm	18.4dBm	17.6dBm
11g	24Mbps	18.28dBm	19.05dBm	18.3dBm
	54Mbps	15.59dBm	16.65dBm	16.32dBm

11n(20MHz)	MCS0	18.68dBm	18.57dBm	18.56dBm
	MCS7	13.32dBm	14.15dBm	14.2dBm

Table 15: Transmitted power

5.3.2 EVM

Mode	Rate	CH1	CH6	CH13
11b	2Mbps	11.01%	11.37%	11.44%
	11Mbps	8.9%	9.8%	9.27%
11g	24Mbps	-18.36	-16.68	-16.91
	54Mbps	-26.68	-25.94	-25.4
11n(20MHz)	MCS0	-16.2	-17.08	-16.92
	MCS7	-31.93	-31.98	-31.77

Table 16: EVM

5.3.3 Receiving sensitivity

Mode	Rate	CH1	CH6	CH13
11b	11Mbps	-89dBm	-89dBm	-89dBm
11g	24Mbps	-84dBm	-84dBm	-85dBm
	54Mbps	-75dBm	-74dBm	-74dBm
11n(20MHz)	MCS0	-91dBm	-91dBm	-90dBm
	MCS7	-71dBm	-70dBm	-70dBm

Table 17: Receiving sensitivity

6. Reference Design

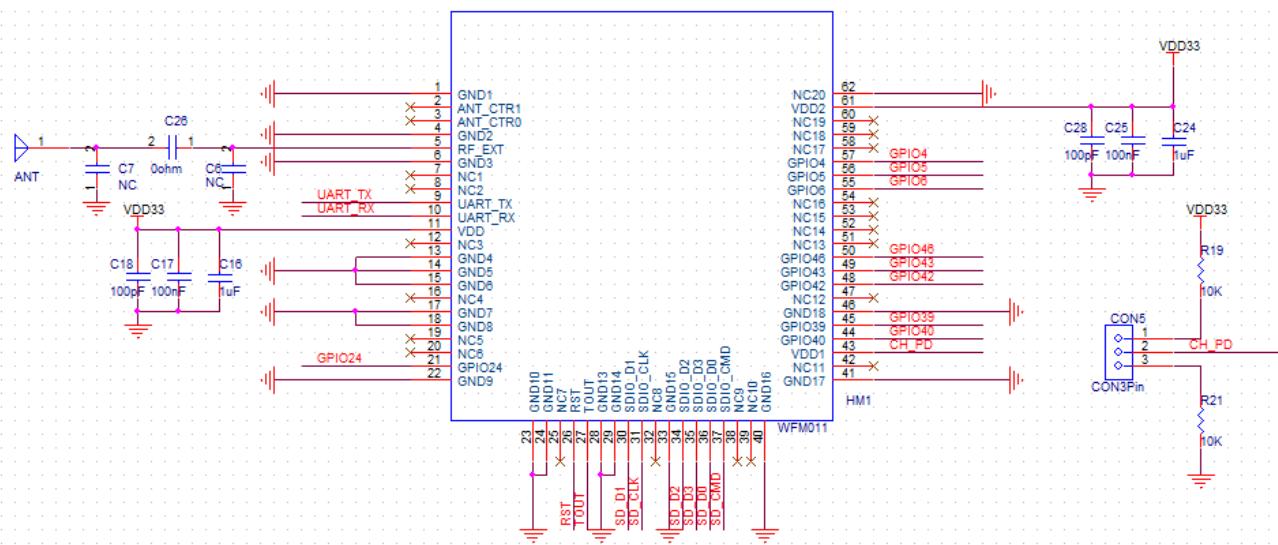


Figure 3: Reference Design

7. Mechanical Characteristic

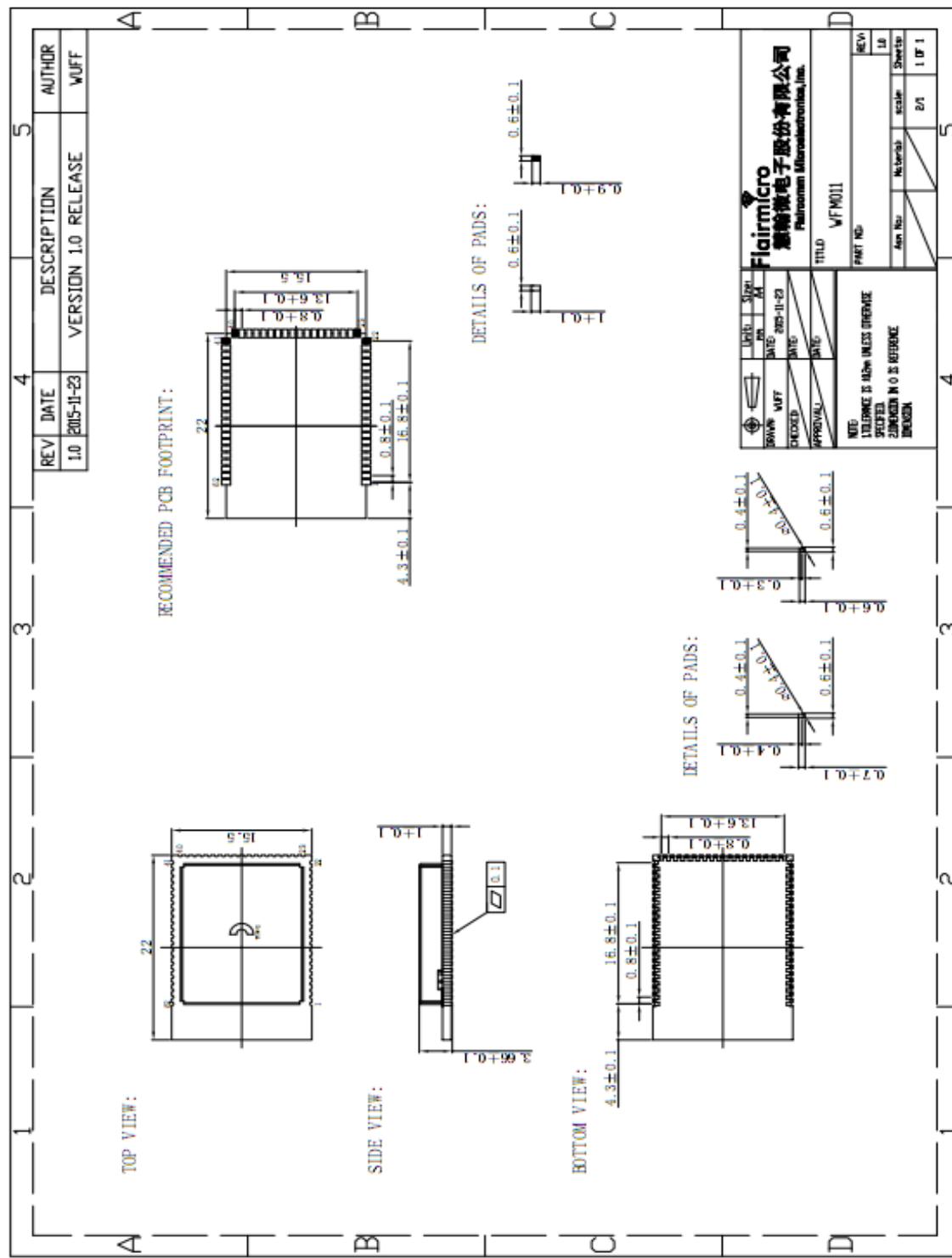


Figure 4: WFM011 Package

8. Recommended PCB layout and mounting pattern

Placement and PCB layout are critical to optimize the performances of a module without on-board antenna designs. The trace from the antenna port of the module to an external antenna should be 50Ω

the transceiver of the module. The location of the external antenna and RF-IN port of the module should be kept away from any noise sources and digital traces. A matching network might be needed in between the external antenna and RF-IN port to better match the impedance to minimize the return loss.

As indicated in Figure 12 below, RF critical circuits of the module should be clearly separated from any digital circuits on the system board. All RF circuits in the module are close to the antenna port. The module, then, should be placed in this way that module digital part towards your digital section of the system PCB.

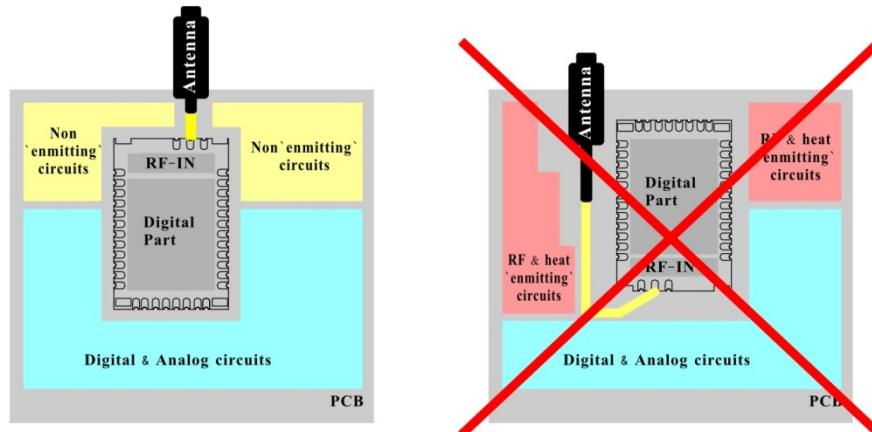


Figure 5: Module on system board

8.1 Antenna connection and grounding plane design

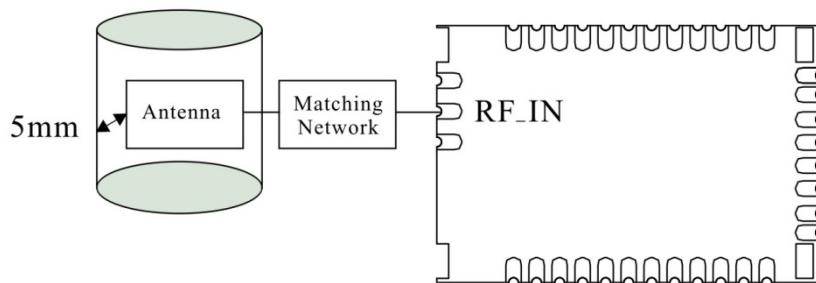


Figure 6: Leave 5mm Clearance Space from the Antenna

General design recommendations are:

- The length of the trace or connection line should be kept as short as possible.

- Distance between RF line connection and ground area on the top layer should at least be as large as the dielectric thickness
- Routing the RF close to digital sections of the system board should be avoided.
- To reduce signal reflections, sharp angles in the routing of the micro strip line should be avoided. Chamfers or fillets are preferred for rectangular routing; 45-degree routing is preferred over Manhattan style 90-degree routing.

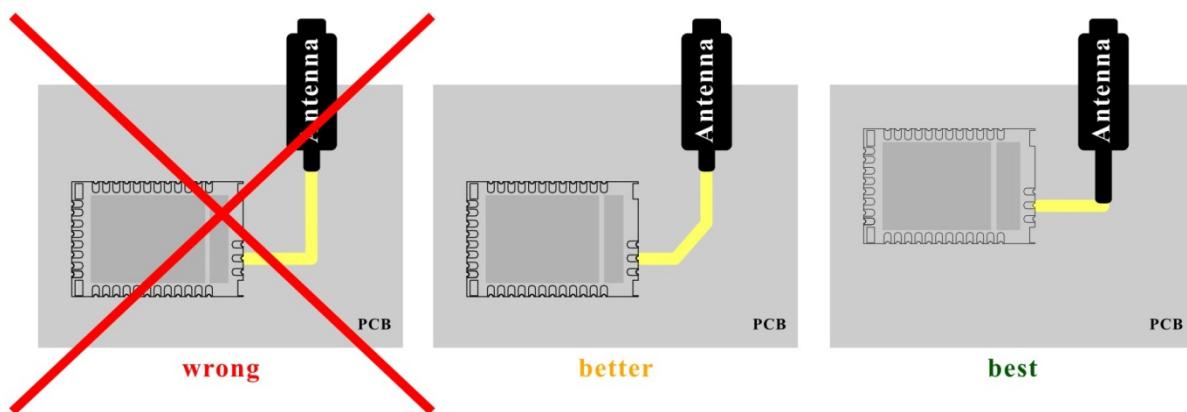


Figure 7: Recommended Trace Connects Antenna and the Module

- Routing of the RF-connection underneath the module should be avoided. The distance of the micro strip line to the ground plane on the bottom side of the receiver is very small and has huge tolerances. Therefore, the impedance of this part of the trace cannot be controlled.

9. Recommended reflow profile

The soldering profile depends on various parameters necessitating a set up for each application. The data here is given only for guidance on solder reflow.

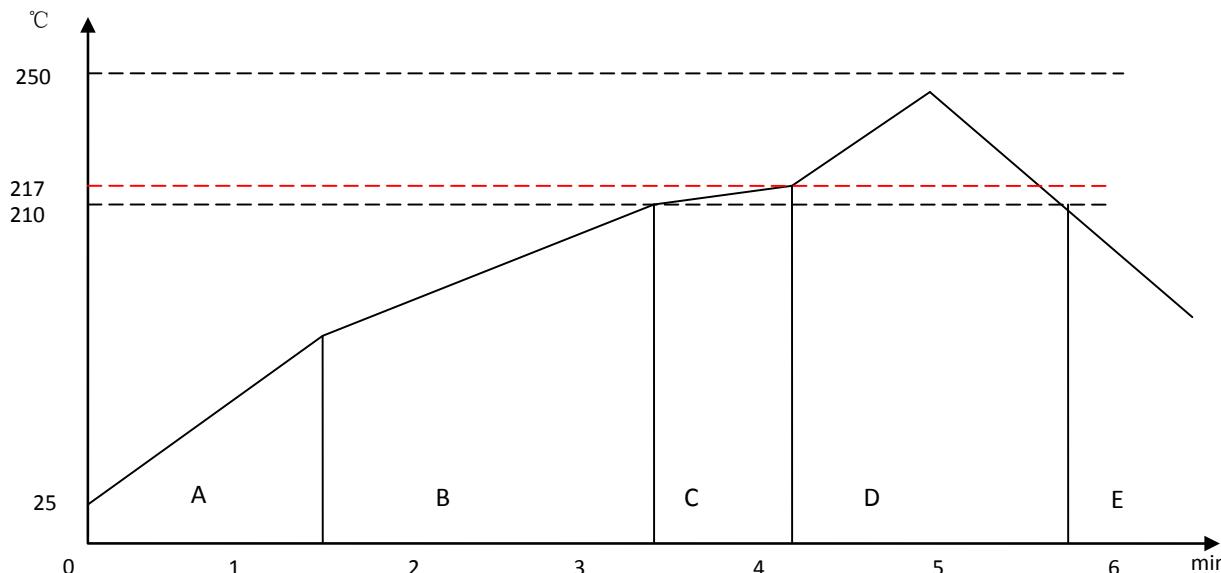


Figure 8: Recommended reflow profile

Pre-heat zone (A)- The purpose of this zone is to preheat the PCB board and components to 120~150°C. This zone raises the temperature to 150°C at a controlled rate, typically 0.5~2 °C .This stage is required to distribute the heat uniformly to the PCB board and completely remove solvent to reduce the heat shock to components. Quick temperature rise will give rise to solder ball because of flying vaporized solvent, and cause component deflection.

Equilibrium zone 1(B)- In this stage the flux becomes soft and uniformly encapsulates solder particles and spread over PCB board.. Compared with infrared oven, hot wind reflow oven commonly applied nowadays enable more uniform temperature transmission, linear temperature rise curve therefore is selected, the board dimension and density and oven efficiency would also be considered. The temperature is recommended to be 150°C to 210°C for about 60 to 120 seconds for this zone.

Equilibrium zone 2(C) (optional)- In order to resolve the upright component issue, it is recommended to keep the temperature in 210 – 217 °C for about 20-30s.

Reflow zone (D)- reflow zone D-The profile in the figure is designed for Sn/Ag3.0/Cu0.5. It can be a reference for other lead-free solder. And it is necessary to adjust the profile according to technical requirement. The recommended peak temperature (Tp) is 230 ~ 250 °C. The soldering time should be 30 to 90 seconds when the temperature is above 217°C.

Cooling zone E- To quickly cool off board and consolidate welding spot to minimize intermetallic compound layer, facilitate hand-holding and keep volatile matter of scaling powder out from workshop, cooling speed is recommended to be 4°C/s. Quick cooling speed helps to form the fine and compact granular structure, since the large granular structure caused by slow cooling speed would have relatively poor reliability.

10. Order information

10.1 Product packaging information

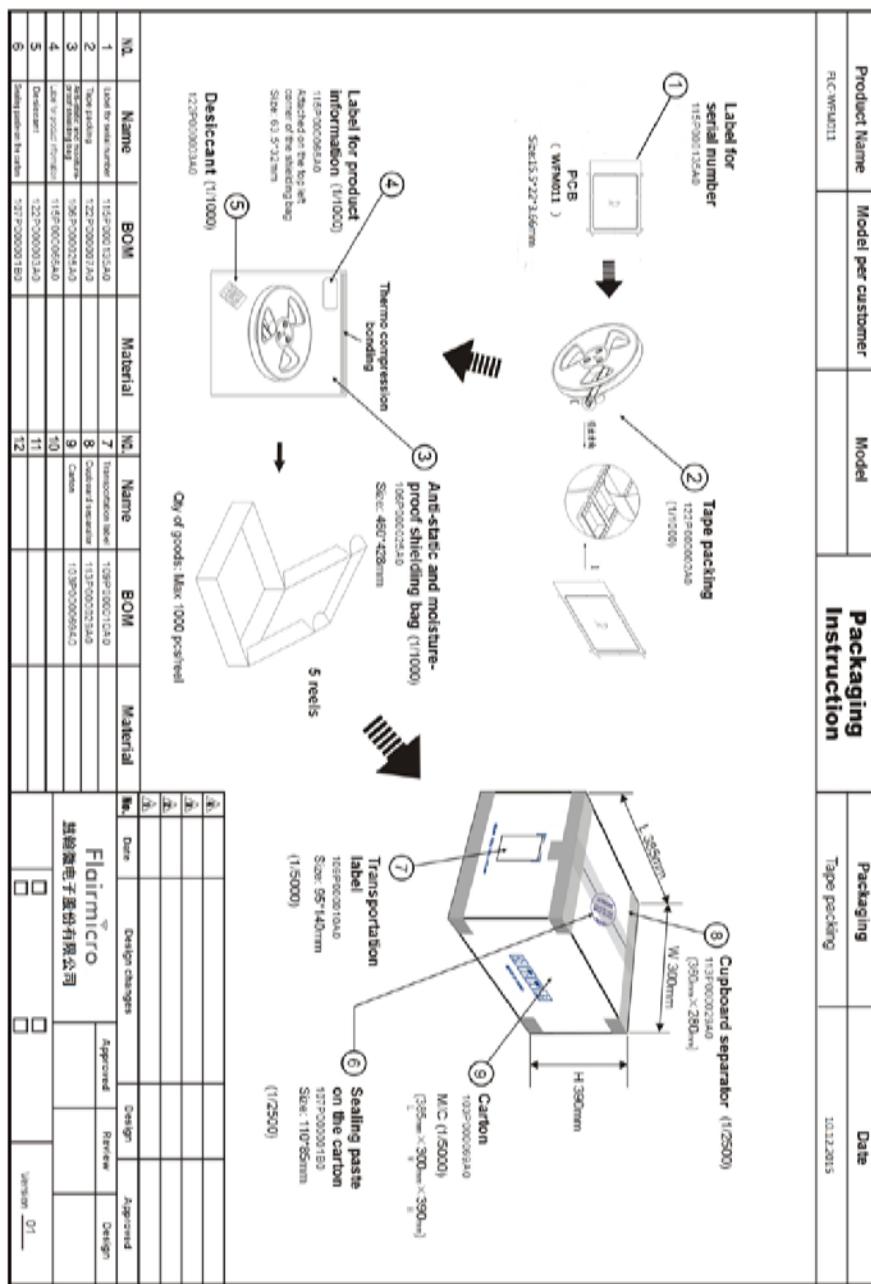
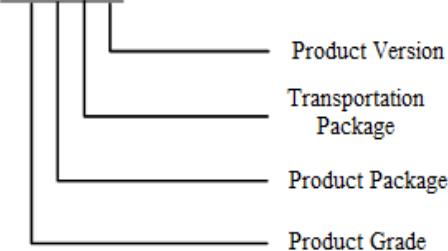


Figure 9: Product package information

10.2 Order information

FLC-WFM011XYZA

**Figure 10: Order Information**

Host Interface	Package		Order Number
	Type	Transportation	
UART	QFN	Tape	WFM011IQ2A

10.2.1 Product Version

Product Version	Description	Availability
A	On-board antenna	Yes
B	External antenna	Yes

Table 18: Product Version**10.2.2 Transportation Package**

Transportation Package	Description	Quantity	Availability
0	Foam Tray	—	No
1	Plastic Tray	—	No
2	Tape	1000	Yes

Table 19: Transportation Package**10.2.3 Product Package**

Product Package	Description	Availability
Q	QFN	Yes

L	LGA	No
B	BGA	No
C	Plug-in	No

Table 20: Product Package**10.2.4 Product Grade**

Product Grade	Description	Availability
C	Consumer	Yes
I	Industrial	Yes
V	Automobile After-Market	No
A	Automobile Before-Market	No

Table 21: Product Grade